

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2295CUP#TRPBF

(Engineering Calculation)

QFN 9mm X 9mm Exp. Pad

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TOTAL MASS (g): 0.224304

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000263	1000000	23463.621994	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.104491	975000	465844.90625	
		Iron (Fe)	7439-89-6	0.002572	24000	11466.5673828	
		Phosphorus (P)	7723-14-0	0.000032	300	142.663160596	
		Zinc (Zn)	7440-66-6	0.000075	700	334.367248535	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-96-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
			<b>Lead Frame Total:</b>		<b>0.107170</b>	<b>1000000</b>	<b>47788.46875</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.003192	1000000	14231.8828125	
			<b>External Plating Total:</b>		<b>0.003192</b>	<b>1000000</b>	<b>14231.8828125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.002279	1000000	10160.3056641	
			<b>Internal Plating Total:</b>		<b>0.002279</b>	<b>1000000</b>	<b>10160.3056641</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001823	750000	8127.35302714	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000608	250000	2710.60375977	
			<b>Die Attach Total:</b>		<b>0.002431</b>	<b>1000000</b>	<b>10837.9506547</b>
		Encapsulation	MULTIAROMATIC RESIN BzSb FREE	Resin (EP)	0.013460	130000	60007.7734375
Bromine (Br)	40093-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.089044	860000	396978.625	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.001035	10000	4614.26757812	
	<b>Encapsulation Total:</b>				<b>0.103539</b>	<b>1000000</b>	<b>461600.625</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000430	1000000	1917.03881836	

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